



# ES2AG THRU ES2JG

Reverse Voltage - 50 to 600 Volts Forward Current - 2.0 Ampere

## SURFACE MOUNT SUPER FAST RECOVERY RECTIFIER

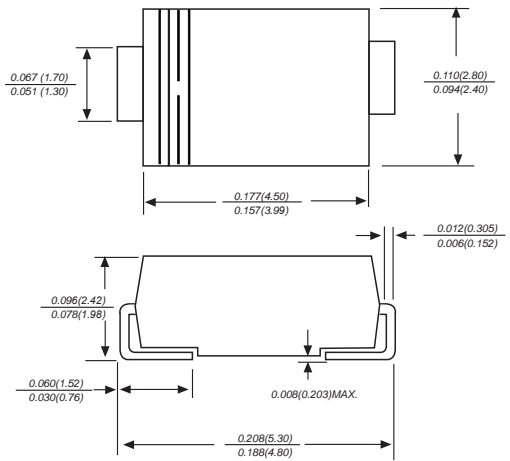
### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
  - ◆ 250°C/10 seconds at terminals
  - ◆ Glass passivated chip junction

### Mechanical Data

**Case :** JEDEC DO-214AC/SMA Molded plastic body  
**Terminals :** Solder plated, solderable per MIL-STD-750, Method 2026  
**Polarity :** Polarity symbol marking on body  
**Mounting Position :** Any  
**Weight :** 0.002 ounce, 0.055 grams

DO-214AC/SMA



Dimensions in inches and (millimeters)

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	ES2AG	ES2BG	ES2CG	ES2DG	ES2EG	ES2GG	ES2JG	UNITS
		MDD ES2A	MDD ES2B	MDD ES2C	MDD ES2D	MDD ES2E	MDD ES2G	MDD ES2J	
Maximum repetitive peak reverse voltage	$V_{RMM}$	50	100	150	200	300	400	600	V
Maximum RMS voltage	$V_{RMS}$	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	$V_{DC}$	50	100	150	200	300	400	600	V
Maximum average forward rectified current at $T_L=55^\circ\text{C}$	$I_{(AV)}$	2.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	50							A
Maximum instantaneous forward voltage at 2.0A	$V_F$	1			1.25		1.68		V
Maximum DC reverse current at rated DC blocking voltage	$I_R$	5.0 / 100.0							$\mu\text{A}$
Maximum reverse recovery time (NOTE 1)	$t_{rr}$	35							ns
Typical junction capacitance (NOTE 2)	$C_J$	40.0							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	60.0							$^\circ\text{C}/\text{W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$

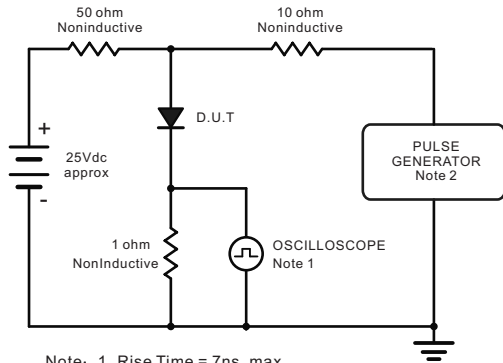
- Note:**
1. Reverse recovery condition  $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$
  2. P.C.B. mounted with 1.0x1.0" (2.54x2.54cm) copper pad areas.
  3. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
  4. The typical data above is for reference only.



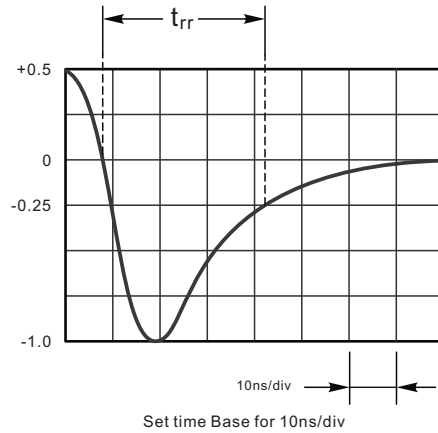
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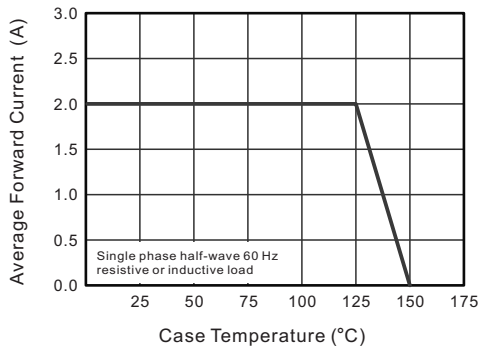
## Ratings And Characteristic Curves



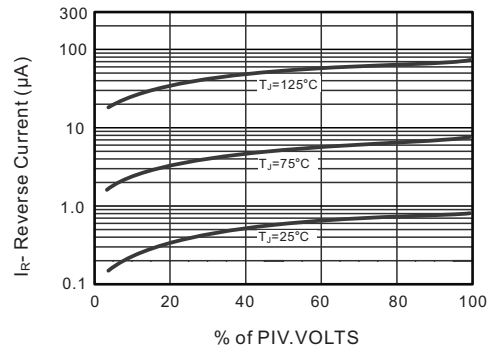
Note: 1. Rise Time = 7ns, max.  
Input Impedance = 1megohm, 22pF.  
2. Rises Time = 10ns, max.  
Source Impedance = 50 ohms.



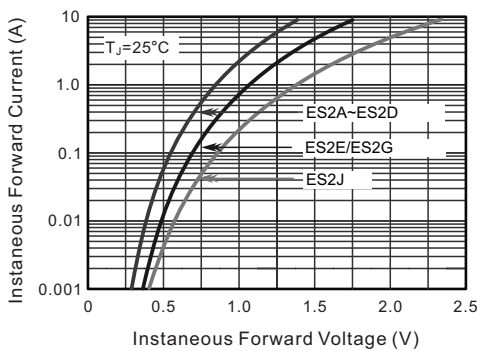
**Fig.2 Maximum Average Forward Current Rating**



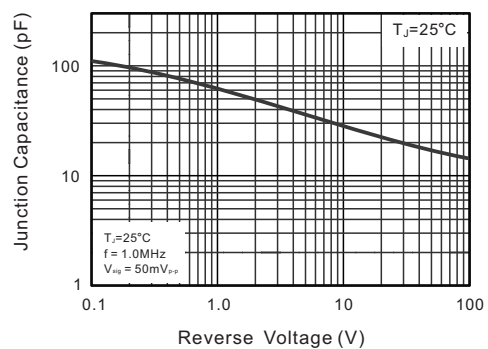
**Fig.3 Typical Reverse Characteristics**



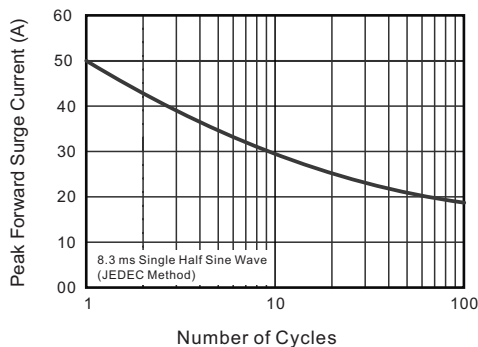
**Fig.4 Typical Forward Characteristics**



**Fig.5 Typical Junction Capacitance**



**Fig.6 Maximum Non-Repetitive Peak Forward Surge Current**



The curve above is for reference only.



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## Packing information



unit:mm

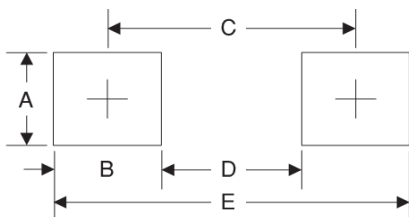
Item	Symbol	Tolerance	SMA
Carrier width	A	0.1	2.80
Carrier length	B	0.1	5.33
Carrier depth	C	0.1	2.36
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D <sub>1</sub>	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D <sub>1</sub>	min	62.00
Feed hole diameter	D <sub>2</sub>	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P <sub>0</sub>	0.1	4.00
Embossment center	P <sub>1</sub>	0.1	2.00
Overall tape thickness	T	0.1	0.28
Tape width	W	0.3	12.00
Reel width	W <sub>1</sub>	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA. (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMA	7"	2,000	4.0	4,000	183*155*183	178	382*356*392	160,000	16.0
SMA	11"	5,000	4.0	10,000	290*290*38	330	310*310*360	80,000	11.0
SMA	13"	7,500	4.0	15,000	335*335*38	330	350*330*360	120,000	14.5

## Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.90	0.154
D	2.41	0.095
E	5.45	0.215

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